

4th December 2018						
07:30-08:30hrs	Registration					
08:30-12:00hrs (210 min)	PDC 1 : Introduction to Fan-out Wafer Level Packaging Dr. Beth Keser Director, Packaging Engineering, Intel Corporation	PDC 2: Advanced Integrated Circuit Design for Reliability Dr. Richard Rao Fellow, Microsemi Corp		PDC 3: 3D SIP For ASIC and DRAM Integration Dr. Li Li Distinguished Engineer, Cisco Systems Inc		
12:00-13:30hrs	Lunch					
13:30-17:00hrs (210 min)	PDC 4 : Understanding Flip Chip Technology and Its Applications Mr. Eric Perfecto Principal Member of the Technical Staff, GLOBALFOUNDRIES	PDC 5: Introduction to 3D Interconnect and Packaging Technologies Prof. Sarah Kim Seoul National University of Science and Technology		PDC 6: Power Electronic Packaging Reliability, Materials, Assembly and Simulation Dr. Ning-Cheng Lee, Vice President of Technology, Indium Corporation Dr. Yong Liu, Principal Member of Tech Staff, ON Semi Prof. Sheng Liu, Dean of the School of Power and Mechanical Engineering and the Institute of Technological Science of Wuhan University		
5th December 2018						
08:00-08:45hrs	Registration					
08:45-09:30hrs (45 min)	Opening Ceremony					
09:30-10:15hrs (45 min)	Keynote 1: Mr. Barber Ivor, Vice President, Packaging Engineering, AMD.					
10:15-10:45hrs (30 min)	Coffee/Tea Break					
10:45-11:30hrs (45 min)	Keynote 2: Dr. Avram Bar-Cohen, Principal Engineering Fellow at Raytheon Corporation and Life Fellow of IEEE.					
11:30-12:15hrs (45 min)	Keynote 3: Mr. David McCann, Vice President, Packaging Test, Development and Operations, GLOBALFOUNDRIES.					
12:15-13:30hrs (75 min)	EPS Luncheon					
13:30-15:30hrs (120 min)	Plenary Session 1: Heterogeneous Packaging 1. Dr. William Chen, ASE Fellow and Senior Technical Advisor 2. Dr. Eric Beyne, Fellow and Program Director, IMEC 3. Dr. Gamal Refai-Ahmed, Distinguished Engineer, Xilinx 4. Mr. Mike Delaus, Manager, Analog 5. Mr. Manish Ranjan, Director, Lam Research					
15:30-16:00hrs (30 min)	Coffee/Tea Break					
16:00-18:00hrs (120 min)	Plenary Session 2: Packaging for next generation automobiles/autonomous vehicles 1. Mr. Gaurab Majumdar, Director, Mitsubishi Electric 2. Ms. LC Tan, Sr. Director, NXP 3. Mr. Christophe BOUQUET, Director, Infineon					
18:30-20:30hrs	VIP Dinner					
6th December 2018						
08:30-09:00hrs (30 min)	Invited #1 : Mr.Sam Karikalan	Invited #2 : Dr. Evelyn Napetschning	Invited #3 : Dr. Yuan Yuan Zhou	Invited #4 : Dr. Gokul Kumar	Invited #5 : Dr. Robert Kao	
09:00-10:00hrs (60 min)	Advanced Packaging Session 1	Interconnect Technologies Session 1	Materials and Processing Session 1	Emerging Technologies Session 1	Thermal Characterization & Cooling Solutions Session 1	
10:00-11:00hrs (60 Min)	Coffee/Tea break & Interactive Session I Exhibitor Presentation 1					
11:00-12:20hrs (80 min)	Advanced Packaging Session 2	Quality, Reliability & Failure Analysis Session 1	Materials and Processing Session 2	Electrical Simulation & Characterization Session 1	Thermal Characterization & Cooling Solutions Session 2	
12:20-13:50hrs (90 min)	Lunch ; Best paper Award, EPTC 2018 committee Appreciation					
13:50-14:20hrs (30 min)	Invited #6 : Dr. Han-Ping Pu	Invited #7 : Dr. Kedar Hardikar	Invited #8: Dr.Dongshun Bai	Invited #9: Ms.Tanja Braun	Invited #10 : Dr. Stevan Hunter	
14:20-15:40hrs (80 min)	TSV & WLB Packaging Session 1	Quality, Reliability & Failure Analysis Session 2	Materials and Processing Session 3	Emerging Technologies Session 2	Electrical Simulation & Characterization Session 2	
15:40-16:40hrs (60 min)	Coffee/Tea break & Interactive Session 1 Exhibitor Presentation 2					
16:40-18:00hrs (80 min)	Thermal Characterization & Cooling Solutions Session 3	Interconnect Technologies Session 2	Materials and Processing Session 4	Emerging Technologies Session 3	Mechanical Simulation & Characterization Session 1	
18:30-21:30hrs (180 min)	Conference Banquet					
7th December 2018						
08:30-09:00hrs (30 min)	Invited #11 : Dr. Soon-Wook Kim	Invited #12 : Mr.Kei Murayama	Invited #13: Mr. Shunsuke Tonouchi	Invited #14 : Ms.Rozalia Beica	Invited #15	
09:00-10:20hrs (80 min)	TSV & WLB Packaging Session 2	Interconnect Technologies Session 3	Materials and Processing Session 5	Emerging Technologies Session 4	Mechanical Simulation & Characterization Session 2	
10:20-11:10hrs (50 min)	Coffee/Tea break & Interactive Session 2 Exhibitor Presentation 3					
11:10-12:30hrs (80 min)	Thermal simulation and Mechanical modeling	Interconnect Technologies Session 4	Electrical Simulation & Characterization Session 3	Equipment and Process Automation	Mechanical Simulation & Characterization Session 3	
12:30-13:30 hrs (60 min)	Lunch ; EPTC 2019 Introduction					
13:30-14:00hrs (30 min)	Invited #16: Mr. Minwoo Daniel Rhee	Invited #17	Invited #18: Prof. Jeff Suhling	Invited #19 : Prof. David Harvey	Invited #20 Mr. Albert Lan	
14:00-15:20hrs (80 min)	TSV & WLB Packaging Session 3	Interconnect Technologies Session 5	Quality, Reliability & Failure Analysis Session 3	Emerging Technologies Session 5	Advanced Packaging Session 3	
15:20-15:40hrs (20 min)	Coffee/Tea break & Interactive Session 2					
15:40-17:40hrs (120 min)	Plenary session 3 : Next Generation Packaging Technologies 1. Yasumitsu Orii, NAGASE "Packaging Technologies for Brain-inspired Devices in the era of AI/IoT" 2. Yasushi Masuda, Fujitsu Advanced Technologies "Challenges and opportunities of packaging technologies for next generation computer systems" 3. Hideyuki Nasu, Furukawa Electric"VCSEL-based Optical Interconnects" 4. Toshihisa Nonaka, Hitachi Chemical "Material technology can drive advanced packaging"					
17:40-18:00hrs (20 min)	Closing Ceremony and Lucky Draw					

Heterogeneous Integration Roadmap Workshop
(Parallel Session to Technical paper tracks)